



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPU80R2K0P7	Issued	27. April 2022
MA#	MA005728150		
Package	PG-TO251-3-23	Weight*	384.47 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.085	0.28	0.28	2823	2823
leadframe	inorganic material	phosphorus	7723-14-0	0.070	0.02		182	
	non noble metal	iron	7439-89-6	0.233	0.06		607	
	non noble metal	copper	7440-50-8	233.116	60.64	60.72	606330	607119
wire	non noble metal	aluminium	7429-90-5	0.192	0.05	0.05	499	499
encapsulation	organic material	carbon black	1333-86-4	0.424	0.11		1102	
	plastics	epoxy resin	-	16.523	4.30		42975	
	inorganic material	silicondioxide	60676-86-0	124.273	32.32	36.73	323231	367308
leadfinish	non noble metal	tin	7440-31-5	7.055	1.83	1.83	18349	18349
solder	non noble metal	tin	7440-31-5	0.030	0.01		78	
	noble metal	silver	7440-22-4	0.038	0.01		98	
	non noble metal	lead	7439-92-1	1.433	0.37	0.39	3726	3902
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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